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ABSTRACT

A package for an integrated circuit contacting device which is shaped like a frame. A portion of the contacting device may be bonded to the printed circuit board, and includes leads which extend along in outer surface thereof, from an outside edge of the package to a downward facing surface of the package which faces an integrated circuit die. The package may be indented in the shape of the die, and may also include indentations allowing a lid and/or a back portion to be located thereon. In an embodiment, a lens amounts may also be used.

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